

In the specification:

Page 9, amend the first paragraph (lines 1-10):

Upper pole piece 22 includes a seed layer 36 and an electroplated layer 38. Upper pole piece 24 includes a seed layer 40 and an electroplated layer 42. Electroplated layers 38 and 42 are formed entirely of a nickel-iron alloy having a body-centered cubic (BCC) structure with from about 64% to about 81% iron by weight. The preferred electroplating process for providing the necessary composition and BCC structure in the electroplated nickel-iron alloy layer is described in the commonly-assigned U.S. Patent Application No. 10/053,785 filed ~~on even date herewith~~ (~~Assignee Docket No. SJ09-2000-0194~~) November 8, 2001 entitled "A Method for Electroplating a Body-Centered Cubic Nickel-Iron Alloy Thin Film with a High Saturation Flux Density," which is entirely included herein by reference.

Page 12, amend the paragraph beginning at line 4 and ending at line 22:

Write head portion 106 of magnetic head 80 includes a coil layer 120 sandwiched between first and second insulation layers 122 and 124. A third insulation layer 126 may be employed for planarizing the head to eliminate ripples in second insulation layer 124 caused by coil layer 120. First, second and third insulation layers 122-126 are referred to in the art as an "insulation stack." Coil layer 120 and first, second and third insulation layers 122, 124 and 126 are sandwiched between the first (P1) and second (P2) pole piece layers ~~[[126]]~~ 127 and 128, which are magnetically coupled at a back gap (yoke) 130. First (P1) and second (P2) pole piece layers ~~[[126]]~~ 127 and 128 each include respective seed layers 132 and 134 and electroplated layers 136 and 138 and have first and second pole tips 140 and 142, which are separated by a write gap layer 144 at the ABS 88. If desired, an insulation layer 146 may be located between second shield (S2) layer 118 and the first pole piece seed layer 134, but it is not necessary for proper operation of this invention. Because the second shield layer 118 and the first pole piece layer ~~[[126]]~~ 127 are separate layers, this head geometry is commonly denominated a "piggyback" read/write head. As shown in Figs. 4, 6 and 10, the first and second solder connections 148 and 150 connect leads from magnetic sensor 110 to the leads 152 and 154 on suspension 82, and the third and fourth solder connections 156 and 158 connect the leads 160 and 162 from coil 120 (see Fig. 10) to the leads 164 and 166 on suspension 82.